

2N682, 2N683, 2N685 – 2N692 and 2N5206



PNPN SILICON, REVERSE-BLOCKING, POWER TRIODE THYRISTORS

Qualified per MIL-PRF-19500/108

DESCRIPTION

This silicon controlled rectifier device is military qualified up to a JANTX level for high-reliability applications. Microsemi also offers numerous other products to meet higher and lower power voltage regulation applications.

Important: For the latest information, visit our website http://www.microsemi.com.

FEATURES

- JEDEC registered 2N682, 2N683, 2N685, 2N687 2N692 and 2N5206.
- JAN and JANTX qualifications are available per MIL-PRF-19500/108.
- RoHS compliant versions available (commercial grade only).



• A general purpose, reverse-blocking thyristor.

MAXIMUM RATINGS

Parameters/Test Conditions	Symbol	Value	Unit
Junction Temperature	TJ	-65 to +125	°C
Storage Temperature	T _{STG}	-65 to +150	°C
Gate Voltage	V _{GM}	5	V(pk)
Maximum Average DC Output Current (1)	lo	16	А
Non-repetitive Peak On-State Current ⁽²⁾ @ t = 7 ms	I _{TSM}	150	А

Notes: 1. This average forward current is for a maximum case temperature of +65 °C, and 180 electrical degrees of conduction.

 Surge rating is non-recurrent and applies only with device in the conducting state. The peak rate of surge current must not exceed 100 amperes during the first 10 μs after switching from the off (blocking) state to the on (conducting) state. This time is measured from the point where the thyristor voltage has decayed to 90 percent of its initial blocking value.

MSC – Lawrence

6 Lake Street, Lawrence, MA 01841 Tel: 1-800-446-1158 or (978) 620-2600 Fax: (978) 689-0803

MSC – Ireland

Gort Road Business Park, Ennis, Co. Clare, Ireland Tel: +353 (0) 65 6840044 Fax: +353 (0) 65 6822298

Website:

www.microsemi.com



Qualified Levels:

JAN and JANTX

TO-208 / TO-48 Package



MECHANICAL and PACKAGING

- CASE: Nickel plated copper.
- TERMINALS: Nickel plated steel, solder dipped.
- MARKING: Manufacturer's ID, part number, date code, polarity.
- POLARITY: Terminal 1: gate, terminal 2: cathode, terminal 3 (stud): anode.
- WEIGHT: 12.36 grams.
- See Package Dimensions on last page.

PART NOMENCLATURE



SYMBOLS & DEFINITIONS				
Symbol	Definition			
V _{AA}	Anode power supply voltage (dc).			



ELECTRICAL CHARACTERISTICS

Parameters / Test Conditions		Symbol	Min.	Max.	Unit
Repetitive Peak Reverse Voltage	2N682	$V_{RRM}^{(1)}$		50	V (pk)
And	2N683	and		100	
Repetitive Peak Off-State Voltage	2N685	V _{DRM}		200	
	2N686			250	
	2N687			300	
	2N688			400	
	2N689			500	
	2N690			600	
	2N691			700	
	2N692			800	
	2N5206			1,000	

(1) Values applicable to zero or negative gate voltage (V_{GM}).

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Holding current: Bias condition D; $V_{AA} = 24$ V maximum; $I_{TM} = I_{F1} = 1$ A $I_T = I_{F2} = 100$ mA trigger voltage source = 10 V trigger PW = 100 µs (minimum) $R_2 = 20 \Omega$	I _H		50	mA
Reverse blocking current AC method, bias condition D; $f = 60 \text{ Hz}, V_{RRM} = rated$	I _{RRM1}		2	mA (pk)
Forward blocking current AC method, bias condition D; f = 60 Hz; V _{DRM} = rated	I _{DRM1}		2	mA (pk)
Gate trigger voltage and current $V_2 = V_D = 6 V; R_L = 50 \Omega;$ $R_e = 20 \Omega$ maximum	V _{GT1} I _{GT1}		3 35	V mA
Forward on voltage $I_{TM} = 50 A(pk) (pulse);$ pulse width = 8.5 ms; maximum; duty cycle = 2 percent maximum	V _{TM}		2	V (pk)
Reverse gate current $V_G = 5 V$	I _G		250	mA



ELECTRICAL CHARACTERISTICS (continued)

Parameters / Test Conditions		Symbol	Min.	Max.	Unit
Reverse blocking current ($T_c = +120 \text{ °C}$) AC method, bias condition D; f = 60 Hz; V _{RRM} = rated		I _{RRM2}		5	mA (pk)
Forward blocking current ($T_c = +120 \text{ °C}$) AC method, bias condition D; $f = 60 \text{ Hz}$; $V_{DRM} = \text{rated}$		I _{DRM2}		5	mA (pk)
Gate trigger voltage ($T_c = +120 \ {}^{\circ}C$; $R_e = 20 \ \Omega max$) $V_2 = V_{DM} = 50 \ V$; $R_L = 140 \ \Omega$ $V_2 = V_{DM} = 100 \ V$; $R_L = 140 \ \Omega$ $V_2 = V_{DM} = 200 \ V$; $R_L = 140 \ \Omega$ $V_2 = V_{DM} = 250 \ V$; $R_L = 650 \ \Omega$ $V_2 = V_{DM} = 300 \ V$; $R_L = 650 \ \Omega$ $V_2 = V_{DM} = 400 \ V$; $R_L = 3 \ k \ \Omega$ $V_2 = V_{DM} = 500 \ V$; $R_L = 3 \ k \ \Omega$ $V_2 = V_{DM} = 600 \ V$; $R_L = 3 \ k \ \Omega$ $V_2 = V_{DM} = 800 \ V$; $R_L = 3 \ k \ \Omega$ $V_2 = V_{DM} = 1,000 \ V$; $R_L = 3 \ k \ \Omega$	2N682 2N683 2N685 2N686 2N687 2N688 2N689 2N690 2N691 2N692 2N5206	V _{GT2}	.25		V
Reverse blocking current ($T_c = -65 \text{ °C}$) AC method, bias condition D; f = 60 Hz; V _{RRM} = rated		I _{RRM3}		2	mA (pk)
Forward blocking current ($T_c = -65 \ ^{\circ}C$) AC method, bias condition D; f = 60 Hz; V _{DRM} = rated		I _{DRM3}		2	mA (pk)
Gate trigger voltage and current ($T_c = -65 \ ^{\circ}C$) V ₂ = V _D = 6 V; R _L = 50 Ω; R _e = 20 Ω maximum				3 80	V mA
Exponential rate of voltage rise Bias condition D; $T_c = +120^{\circ}C$ minimum, dv/dt = 25 v/µs; repetition rate = 60 pps; test duration = 15 s; $C = 1.0 \mu$ F; $R_L = 50 \Omega$ $V_{AA} = 50 V$ $V_{AA} = 100 V$ $V_{AA} = 200 V$ $V_{AA} = 200 V$ $V_{AA} = 250 V$ $V_{AA} = 300 V$ $V_{AA} = 400 V$ $V_{AA} = 500 V$ $V_{AA} = 600 V$ $V_{AA} = 700 V$ $V_{AA} = 800 V$ $V_{AA} = 1,000 V$	2N682 2N683 2N685 2N686 2N687 2N688 2N689 2N690 2N691 2N692 2N5206	VD	47 95 190 240 285 380 475 570 665 760 950		~



ELECTRICAL CHARACTERISTICS (continued)

Parameters / Test Conditions			Min.	Max.	Unit
Circuit-commutated turn-off time $T_c = +120^{\circ}C$ minimum; $I_{TM} = 10 A$; $t_{on} = 100 \pm 50 \mu$ s; di/dt = 5 A/µs minimum; di/dt = 8 A/µs maximum; reverse voltage at $t_1 = 15$ V repetition rate = 60 pps maximum; di/dt = 20 V/µs; gate bias conditions; gate source voltage = 0 V; gate source resistance = 100 Ω $V_{DM} = V_{DRM} = 50 V (pk); V_{RRM} = 50 V maximum$ $V_{DM} = V_{DRM} = 100 V (pk); V_{RRM} = 100 V maximum$ $V_{DM} = V_{DRM} = 200 V (pk); V_{RRM} = 200 V maximum$ $V_{DM} = V_{DRM} = 300 V (pk); V_{RRM} = 300 V maximum$ $V_{DM} = V_{DRM} = 300 V (pk); V_{RRM} = 300 V maximum$ $V_{DM} = V_{DRM} = 500 V (pk); V_{RRM} = 500 V maximum$ $V_{DM} = V_{DRM} = 500 V (pk); V_{RRM} = 600 V maximum$ $V_{DM} = V_{DRM} = 600 V (pk); V_{RRM} = 600 V maximum$ $V_{DM} = V_{DRM} = 700 V (pk); V_{RRM} = 800 V maximum$ $V_{DM} = V_{DRM} = 800 V (pk); V_{RRM} = 1,000 V maximum$	/ minimum; 2N682 2N683 2N685 2N686 2N687 2N688 2N689 2N690 2N691 2N692 2N5206	t _{off}		30 30 30 30 30 30 40 40 60 60 60	μs
Gate controlled turn-on time $V_{AA} = 50 \text{ V}$ for 2N682 $V_{AA} = 100 \text{ V}$ for 2N683, 2N685 through 2N692 and 2N5206 $I_{TM} = 10 \text{ A}; V_{GG} = 10 \text{ V}; \text{ R}_{e} = 25 \Omega$ $t_{p1} = 15 \pm 5 \mu\text{s}; 4 \text{ A}/\mu\text{s} \le \text{ di/dt} \le 200 \text{ A}/\mu\text{s}.$	2N682, 2N683, 2N685 through 2N692 & 2N5206	t _{on}		5	μS



PACKAGE DIMENSIONS



NOTES:

- 1. Dimensions are in inches. Millimeters are given for general information only.
- 2. Device contour, except on hex head and noted terminal dimensions, is optional within zone defined by CD and OAH, CD not to exceed actual HF.
- 3. Contour and angular orientation of terminals 1 and 2 with respect to hex portion and to each other are optional.
- 4. Chamfer or undercut on one or both ends of the hexagonal portion are optional.
- 5. Square or radius on end of terminal is optional.
- 6. Minimum difference in terminal lengths to establish datum line for numbering terminals.
- 7. Dimension SD is pitch diameter of coated threads.
- 8. In accordance with ASME Y14.5M, diameters are equivalent to Φx symbology.

Ltr	Inc	hes	Millimeters		Notes
	Min	Max	Min	Max	
b	.115	.139	2.92	3.53	3
b1	.210	.300	5.33	7.62	3
CD		.543		13.8	2
СН		.550		14.00	
e2	.125		3.17		6
HF	.544	.563	13.8	14.3	
HT	.075	.200	1.9	5.08	4
OAH		1.193		30.3	2
S	.120		3.05		3
SD		1⁄4 - 28 l	JNF 2A	JNF 2A	
SL	.422	.453	10.7	11.5	
SU		.090		2.29	
ФТ	.125	.165	3.17	4.19	
ΦT1	.060	.075	1.52	1.9	
UD	.220	.249	5.59	6.32	

Terminal 1	Gate	
Terminal 2	Cathode	5
Terminal 3	Anode (Stud)	7